IEEE802.11a Based Wireless AV Module(WAVM) with Digital AV Interface

TOSHIBA Corp.

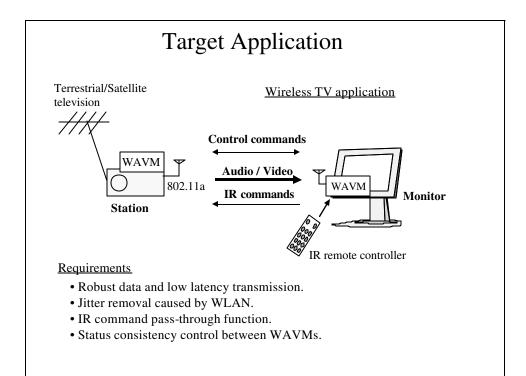
<u>T.Wakutsu</u>, N.Shibuya, E.Kamagata, T.Matsumoto, Y.Nagahori, T.Sakamoto, Y.Unekawa, K.Tagami, M.Serizawa

#### Outline

- Background
- Key techniques
  - Timing jitter removal function for MPEG2 TS data
  - IR command path-through
  - IIC I/F function
  - Status consistency control
- Block diagram
- Experiment results
- Conclusions

### Background

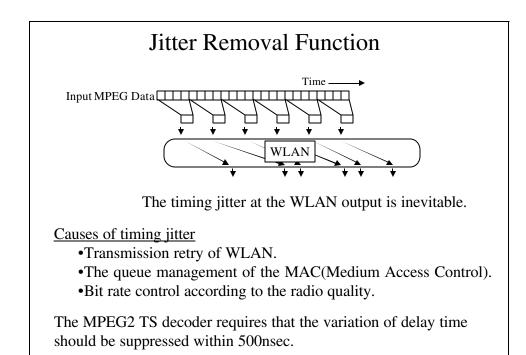
- Enhancement of IEEE802.11 standard is continuing.
  b, g, a, e, h, i, n and so on...
- WLAN became very popular for PC applications.
- Wireless feature is attractive for non-PC applications.
  - VoWLAN
  - Wireless Audio/Video(AV) transfer
- PC peripheral WLAN equipments are not directly applicable to the non-PC applications.
- AV application requires the AV specific capability.
- WAVM(Wireless Audio / Video Module)
  - Specific LSI equipped with AV I/Fs has been developed.
  - Proprietary protocol is defined for the AV data transmission because the standardization is not finalized yet.

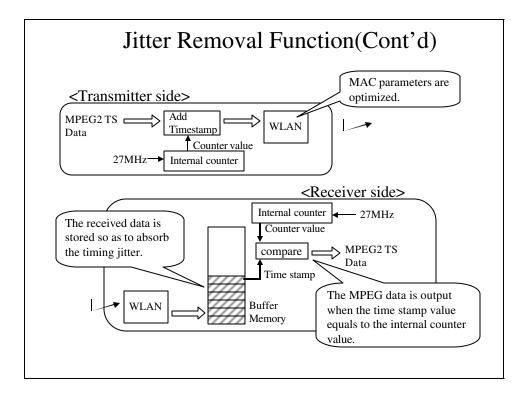


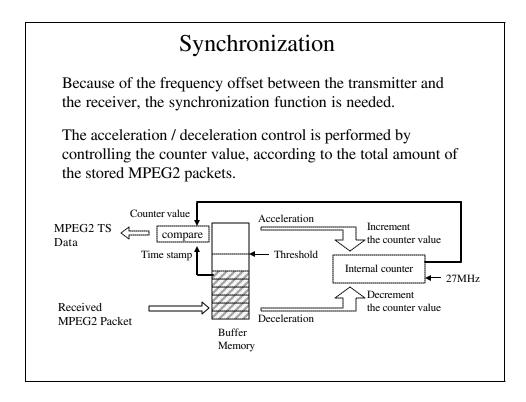
# Key Techniques of WAVM

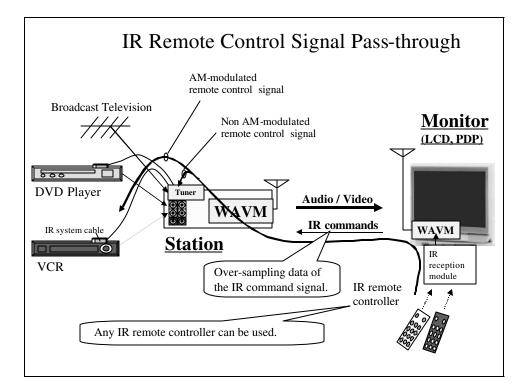
•Jitter removal function for MPEG2 data.

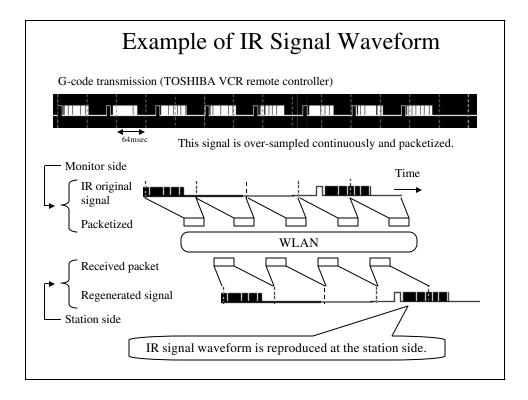
- •IR remote control signal pass-through.
- •IIC bus interface.
- •Status consistency control.
- •Module partitioning.
- •WAVM architecture.

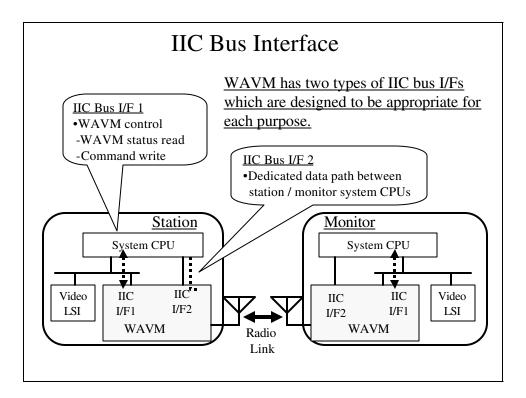


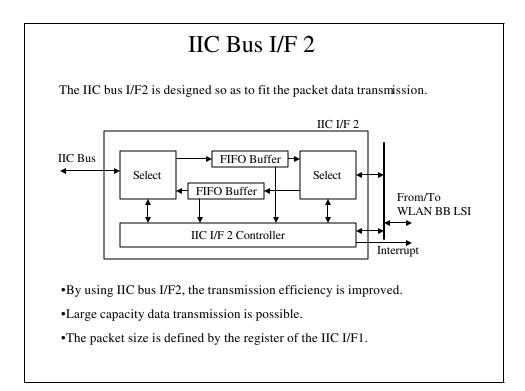


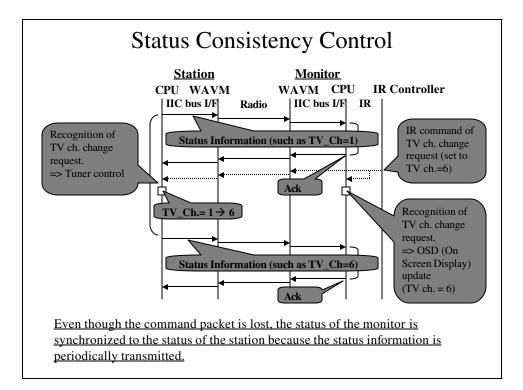


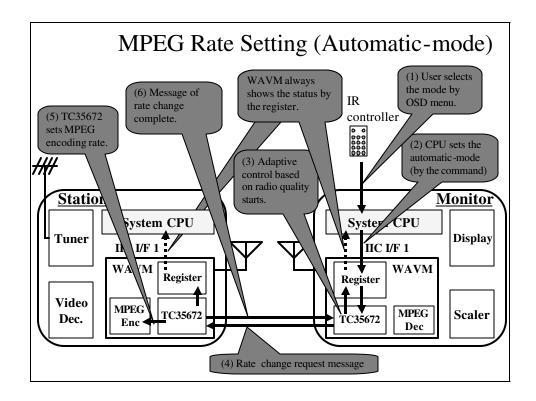








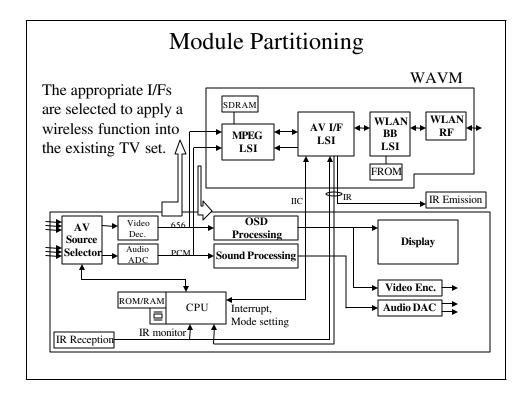


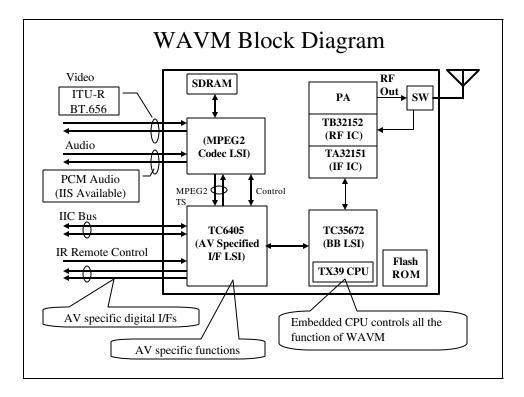


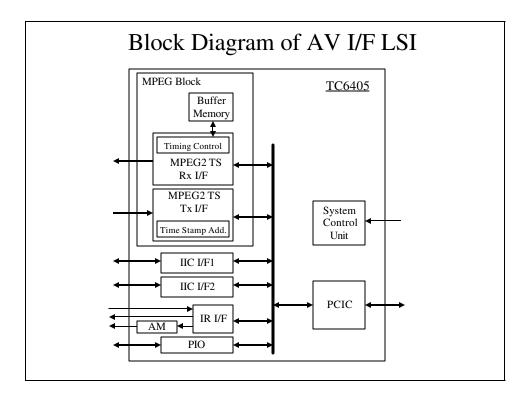
# Key Techniques of WAVM

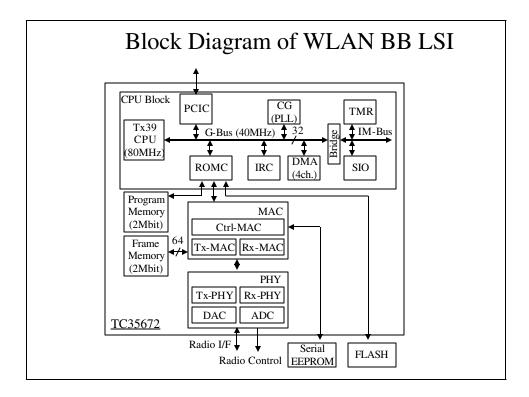
•Jitter removal function for MPEG2 data.

- •IR remote control signal pass-through.
- •IIC bus interface.
- •Status consistency control.
- •Module partitioning.
- •WAVM architecture.

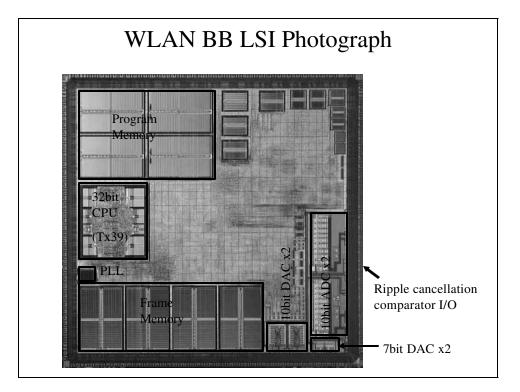


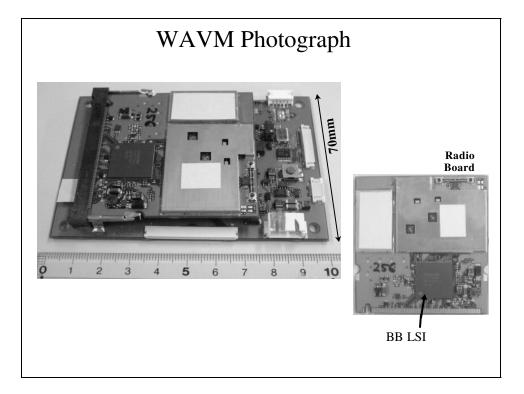






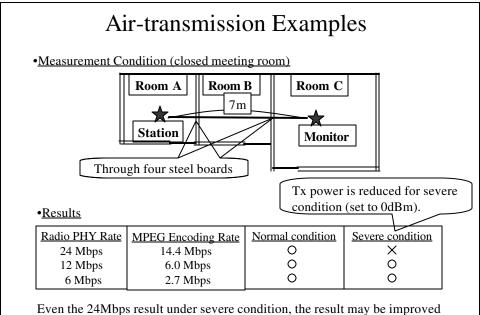
	Chip Features
LAN LSI(TC	<u>35672)</u>
Process	0.18um CMOS 6layer metal
	(Random: 1.27Mgates, Memory: 4.29Mbits)
Chip Size	10.9 x 10.9 mm
Package	361pin PFBGA(Plastic Fine pitch Ball Grid Array)
Supply Voltage	Core: 1.5V, Analog: 2.5V, I/O: 3.3V
Frequency	20/40/80MHz
/ I/F LSI(TC	<u>5405)</u>
Process	0.18um CMOS 5layer
Process	0.18um CMOS 5layer (Random: 251Kgates, Memory: 1.63Mbits)
Process Chip Size	2
	(Random: 251Kgates, Memory: 1.63Mbits)
Chip Size	(Random: 251Kgates, Memory: 1.63Mbits) 7.1 x 7.1 mm





### WAVM Features

- Wireless audio/video transmission
  - Timing jitter removal to satisfy MPEG2-TS delay spread
  - WLAN parameters are optimized for AV data transmission.
  - Using clear 5GHz band WLAN (suitable to the home application)
  - Packet by packet selection antenna diversity.
  - High performance super heterodyne radio architecture.
- Easy-add-on to an existing TV system.
- All-in-one module including an MPEG2 encoder/decoder LSI
  - Embedded CPU in BB LSI controls all the function of WAVM.
    - No additional CPU is used in WAVM.
  - AV I/F LSI equipped with the AV specific function and I/Fs.
  - Status consistency control.
- Small size
  - 70 x 100 x 11 mm



if antenna arrangement is optimized.

# Conclusions

- WAVM achieved all the necessary features for home AV application.
  - Simplest wireless function extension into the conventional TV set.
  - All-in-One module including an MPEG2 Encoder/Decoder LSI.
  - Provides AV specific function.
  - Rapid wake up.
  - Short latency control (Ex. tuner ch. change time).
- Future plan
  - Digital HD (High Definition) stream transmission with secure content protection.
  - AV transmission protocol standardization.

